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	Application No.	Applicant(s)	
Notice of Allowability	09/015,287	NOZAKI ET AL.	
	Examiner	Art Unit	
	John S. Chu	1752	
The MAILING DATE of this communication apperall claims being allowable, PROSECUTION ON THE MERITS IS therewith (or previously mailed), a Notice of Allowance (PTOL-85) NOTICE OF ALLOWABILITY IS NOT A GRANT OF PATENT RI	(OR REMAINS) CLOSED in the or other appropriate communing GHTS. This application is subsected in the community of the communi	nis application. If not includ cation will be mailed in due	ed course. THIS
1. \square This communication is responsive to $7/21/04$.			
2. ☑ The allowed claim(s) is/are <u>1-18 and 20-28</u> .			
3. \square The drawings filed on are accepted by the Examine	r.		
4. Acknowledgment is made of a claim for foreign priority unally All b) Some* c) None of the: 1. Certified copies of the priority documents have 2. Certified copies of the priority documents have 3. Copies of the certified copies of the priority documents have International Bureau (PCT Rule 17.2(a)). * Certified copies not received: Applicant has THREE MONTHS FROM THE "MAILING DATE" noted below. Failure to timely comply will result in ABANDONM THIS THREE-MONTH PERIOD IS NOT EXTENDABLE. 5. A SUBSTITUTE OATH OR DECLARATION must be submainformal pattent APPLICATION (PTO-152) which give (a) including changes required by the Notice of Draftspers 1) hereto or 2) to Paper No./Mail Date (b) including changes required by the attached Examiner's Paper No./Mail Date Identifying indicia such as the application number (see 37 CFR 1 each sheet. Replacement sheet(s) should be labeled as such in the deponant of the depona	been received. been received in Application cuments have been received in Application of this communication to file a MENT of this application. itted. Note the attached EXAM as reason(s) why the oath or do st be submitted. son's Patent Drawing Review (as Amendment / Comment or in the header according to 37 CFR is it of BIOLOGICAL MATER	No In this national stage application this national stage application this national stage application to the complex of the Office action of the Office action of the 1.121(d). RIAL must be submitted.	equirements NOTICE OF
Attachment(s) 1. Notice of References Cited (PTO-892) 2. Notice of Draftperson's Patent Drawing Review (PTO-948) 3. Information Disclosure Statements (PTO-1449 or PTO/SB/C Paper No./Mail Date 4. Examiner's Comment Regarding Requirement for Deposit of Biological Material	6. ☐ Interview Sur Paper No./M 7. ☐ Examiner's A	rmal Patent Application (PT nmary (PTO-413), lail Date mendment/Comment tatement of Reasons for All John S. Chu Primary Examiner Art Unit: 1752	owance

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REASONS FOR ALLOWANCE

- 1. The following is an examiner's statement of reasons for allowance: The claimed invention is drawn to the following:
 - An acid-sensitive polymer compound, comprising:
 - a film-forming polymer;
 - a carboxyl group bonding to a side chain of said polymer main chain, said carboxyl group having a protective group; and

an additional acidic functional group bonding to a side chain of said polymer main chain, said acidic functional group having an acid-cleavable protective group;

said carboxyl group having, as said protective group, a lactone structure represented by a formula

wherein n is an integer of 1 - 4, and R represents any of a hydrogen atom, an alkyl group, an alkoxyl group or an alkoxycarbonyl group and bonding to an arbitrary position of said lactone structure excluding a second position forming an ester bonding.

8. A resist composition, comprising:

an acid-sensitive film-foming polymer insoluble to an alkaline solution; a carboxyl group bonding to a side chain of said polymer's main chain, said carboxyl group having a protective group; and an additional acidic functional group bonding to a side chain of said polymer main chain, said acidic functional group having an acid-cleavable protective group; said carboxyl group having, as said protective group, a lactone structure represented by a formula

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wherein n is an integer of 1 - 4, and R represents any of a hydrogen atom, an alkyl group, an alkoxyl group or an alkoxycarbonyl group and bonding to an arbitrary position of said lactone structure excluding a second position forming an ester bonding; and

a photoacid generator causing a decomposition in response to an absorption of a radiation, said photoacid generator releasing an acid that causes a deprotection of said acid-cleavable protective group in response to said decomposition;

said resist composition becoming soluble to said alkaline solution after said acid-cleavable protective group has caused said deprotection.

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18 (original): A method of forming a resist pattern, comprising the steps of:

applying a resist composition on a substrate to form a resist film, said resist composition comprising:

an acid-sensitive polymer compound insoluble to an alkaline solution, said acid-sensitive polymer compound comprising a film-forming polymer; a carboxyl group bonding to a side chain of said polymer main chain, said carboxyl group having a protective group; and an additional acidic functional group bonding to a side chain of said polymer main chain, said acidic functional group having an acid-cleavable protective group; said carboxyl group having, as said protective group, a lactone structure represented by a formula

wherein n is an integer of 1 - 4, and R represents any of a hydrogen atom, an alkyl group, an alkoxyl group and an alkoxycarbonyl group and bonding to an arbitrary position of said lactone structure excluding a second position forming an ester bonding; and

a photoacid generator causing a decomposition in response to an absorption of a radiation, said photoacid generator releasing an acid that causes a deprotection of said acid-cleavable Art Unit: 1752

Claim 24 (new): A method of fabricating a semiconductor device, comprising the steps of:

applying a resist composition on a substrate to form a resist film, said resist composition comprising:

an acid-sensitive polymer compound insoluble to an alkaline solution, said acid-sensitive polymer compound comprising a film-forming polymer; a carboxyl group bonding to a side chain of said polymer main chain, said carboxyl group having a protective group; and an additional acidic functional group bonding to a side chain of said polymer main chain, said acidic functional group having an acid-cleavable protective group; said carboxyl group having, as said protective group, a lactone structure represented by formula

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wherein n is an integer of 1-4, and R represents any of a hydrogen atom, an alkyl group, an alkoxyl group or an alkoxycarbonyl group and connected to an arbitrary position of said lactone structure excluding a second position forming an ester bonding; and

a photoacid generator causing a decomposition in response to an absorption of a radiation, said photoacid generator releasing an acid that causes a deprotection of said acid-cleavable protective group in response to said decomposition;

Applicants have cancelled previous claim 19, and have rewritten the same method and inserted the limitations to a "method of fabricating a semiconductor device,".

Support for the amendment to the preamble is found on page 28, lines 10-37. Applicants state that the method of claim 19 should have recited the method as now claimed. The examiner relies on the previous "REASONS FOR ALLOWANCE" as mailed April 21, 2004, because the inventive step to the composition having the particularly claimed 2-hydroxy-alkylolactone group in a polymer remains the same as the inventive step. The

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claims 24-28 are also allowable, wherein a method of using a novel and non-obvious invention is also allowable.

Because none of the prior art references of record disclose the claimed acid polymer, the resist composition, the method of forming a pattern or the method of fabricating a semiconductor device, claims 1-18, 20-28 are seen as allowable and passed to issue.

2. Any inquiry concerning this communication or earlier communications from the examiner should be directed to Examiner Chu whose telephone number is (571) 272-1329. The examiner can normally be reached on Monday - Friday from 9:30 am to 6:00 pm.

The fax phone number for the USPTO is (703) 872-9306.

Any inquiry of a general nature or relating to the status of this application or proceeding should be directed to the Group receptionist whose telephone number is (571) 272-1700.

Information regarding the status of an application may be obtained from the Patent Application Information Retrieval (PAIR) system. Status information for published applications may be obtained from either Private PAIR or Public PAIR. Status information for unpublished applications is available through Private PMR only. For more information about the PAIR system, see http://pair-direct.uspto.gov. Should you

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have questions on access to the Private PAIR system, contact the Electronic Business

Center (EBC) at 866-217-9197 (toll-free).

John S. Chu Primary Examiner, Group 1700

J.Chu September 15, 2004